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(71)Applicant : HITACHI LTD

HITACHI MEDIA ELECTRONICS
CO LTD

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(72)Inventor : FUJIWARA SHINICHI

HARADA MASAhide

MATSUMOTO KUNIO

MATSUZAKI EIJI

(54) ELECTRONIC DEVICE AND ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To form the electronic device of a chip size excellent in sealing property with the reduced number of processes .

SOLUTION: In electronic parts consisted of a chip including a side for functioning and an electrode at least on one side and a substrate having its portion of the chip which is connectable with the electrode of the chip, electrical connection between the chip and the substrate is provided by making use of a conductive glass and an intermetallic compound for the connection part, and simultaneously a device side on the chip is sealed.

